

SLOVENSKI STANDARD SIST EN 60539-1:2016

01-oktober-2016

Nadomešča:

SIST EN 60539-1:2008

Neposredno ogrevani termistorji z negativnim koeficientom - 1. del: Rodovna specifikacija (IEC 60539-1:2016)

Directly heated negative temperature coefficient thermistors - Part 1: Generic specification (IEC 60539-1:2016)

iTeh STANDARD PREVIEW

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Thermistances à coefficient de température négatif à chauffage direct - Partie 1: Spécification générique SIST EN 60539-1:2016

https://standards.iteh.ai/catalog/standards/sist/e0fc057c-01bf-4392-b62c-6620cb5aedb4/sist-en-60539-1-2016

Ta slovenski standard je istoveten z: EN 60539-1:2016

ICS:

31.040.30 Termistorji Thermistors

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<u>SIST EN 60539-1:2016</u> https://standards.iteh.ai/catalog/standards/sist/e0fc057c-01bf-4392-b62c-6620cb5aedb4/sist-en-60539-1-2016 EUROPEAN STANDARD NORME EUROPÉENNE EUROPÄISCHE NORM EN 60539-1

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English Version

Directly heated negative temperature coefficient thermistors Part 1: Generic specification (IEC 60539-1:2016)

Thermistances à coefficient de température négatif à chauffage direct - Partie 1: Spécification générique (IEC 60539-1:2016)

Direkt geheizte temperaturabhängige Widerstände mit negativem Temperaturkoeffizienten -Teil 1: Fachgrundspezifikation (IEC 60539-1:2016)

This European Standard was approved by CENELEC on 2016-06-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

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SIST EN 60539-1:2016

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CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

EN 60539-1:2016

European foreword

The text of document 40/2430/FDIS, future edition 3 of IEC 60539-1, prepared by IEC/TC 40 "Capacitors and resistors for electronic equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60539-1:2016.

The following dates are fixed:

- latest date by which the document has to be implemented at (dop) 2017-03-01 national level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with (dow) 2019-06-01 the document have to be withdrawn

This document supersedes EN 60539-1:2008.

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Endorsement notice

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The text of the International Standard IEC 60539-1:2016 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60027-1 NOTE Harmonized as EN 60027-1.

ISO 80000-1:2009 NOTE Harmonized as EN ISO 80000-1:2013 (not modified).

EN 60539-1:2016

Annex ZA

(normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	EN/HD	<u>Year</u>
IEC 60062	-	Marking codes for resistors and capacitors	EN 60062	-
IEC 60068-1	12013h	Environmental testing PREVIE Part 1: General and guidance	EN 60068-1	2014
IEC 60068-2-1	-	Environmental testing teh.ai) Part 2-1: Tests - Test A: Cold	EN 60068-2-1	-
IEC 60068-2-2	https://standar	Environmental testing 1-2016 Part 2-2: Tests Test B: Dry heat 01bf-4392	EN 60068-2-2 -b62c-	-
IEC 60068-2-6	-	Part 2-2: Tests - Test Bt. Dry heat 01bf-4392 6620cb5aedb4/sist-en-60539-1-2016 Environmental testing - Part 2-6: Tests - Test Fc: Vibration (sinusoidal)	EN 60068-2-6	-
IEC 60068-2-11	-	Basic environmental testing procedures - Part 2-11: Tests - Test Ka: Salt mist	EN 60068-2-11	-
IEC 60068-2-14	-	Environmental testing - Part 2-14: Tests - Test N: Change of temperature	EN 60068-2-14	-
IEC 60068-2-17	-	Basic environmental testing procedures - Part 2-17: Tests - Test Q: Sealing	EN 60068-2-17	-
IEC 60068-2-20	-	Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads	EN 60068-2-20	-
IEC 60068-2-21	-	Environmental testing - Part 2-21: Tests - Test U: Robustness of terminations and integral mounting devices	EN 60068-2-21	-
IEC 60068-2-27	-	Environmental testing - Part 2-27: Tests - Test Ea and guidance: Shock	EN 60068-2-27	-

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<u>Publication</u>	Year	Title	EN/HD	Year
IEC 60068-2-31	<u>-</u>	Environmental testing - Part 2-31: Tests - Test Ec: Rough handling shocks, primarily for equipment-type specimens	EN 60068-2-31	<u>-</u>
IEC 60068-2-38	-	Environmental testing - Part 2-38: Tests - Test Z/AD: Composite temperature/humidity cyclic test	EN 60068-2-38	-
IEC 60068-2-45 + A1	1980 1993	Basic environmental testing procedures - Part 2-45: Tests - Test XA and guidance: Immersion in cleaning solvents	EN 60068-2-45 + A1	1992 1993
IEC 60068-2-52	-	Environmental testing - Part 2-52: Tests - Test Kb: Salt mist, cyclic (sodium chloride solution)	EN 60068-2-52	-
IEC 60068-2-54	-	Environmental testing - Part 2-54: Tests - Test Ta: Solderability testing of electronic components by the wetting balance method	EN 60068-2-54	-
IEC 60068-2-58	- iTeh	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	-
IEC 60068-2-69	- https://standar	Environmental testing - Part 2: Tests - Test Te: Solderability testing of electronic components for dsurface mounting devices (SMD) by the 92 wetting balance method 39-1-2016	EN 60068-2-69 -b62c-	-
IEC 60068-2-78	-	Environmental testing - Part 2-78: Tests - Test Cab: Damp heat, steady state	EN 60068-2-78	-
IEC 60294	-	Measurement of the dimensions of a cylindrical component with axial terminations	EN 60294	-
IEC 60717	-	Method for the determination of the space required by capacitors and resistors with unidirectional terminations	EN 60717	-
IEC 61193-2	-	Quality assessment systems - Part 2: Selection and use of sampling plans for inspection of electronic components and packages	EN 61193-2	-
IEC 61249-2-7	-	Materials for printed boards and other interconnecting structures - Part 2-7: Reinforced base materials, clad and unclad - Epoxide woven E-glass laminated sheet of defined flammability (vertical burning test), copper-clad	EN 61249-2-7	-



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Edition 3.0 2016-04

INTERNATIONAL STANDARD

NORME INTERNATIONALE

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

DIRECTLY HEATED NEGATIVE TEMPERATURE COEFFICIENT THERMISTORS –

Part 1: Generic specification

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International Standard IEC 60539-1 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment.

This third edition cancels and replaces the second edition published in 2008. This edition constitutes a technical revision. Tables, figures and references have been revised.

The text of this standard is based on the following documents:

FDIS	Report on voting
40/2430/FDIS	40/2457/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60539 series, published under the general title *Directly heated negative temperature coefficient thermistors*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- · reconfirmed,
- withdrawn,
- · replaced by a revised edition, or
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DIRECTLY HEATED NEGATIVE TEMPERATURE COEFFICIENT THERMISTORS –

Part 1: Generic specification

1 Scope

This part of IEC 60539 is applicable to directly heated negative temperature coefficient thermistors, typically made from transition metal oxide materials with semiconducting properties.

It establishes standard terms, inspection procedures and methods of test for use in sectional and detail specifications of electronic components for quality assessment or any other purpose.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

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IEC 60062, Marking codes for resistors and capacitors

SIST EN 60539-1:2016

IEC 60068-1:2013, Environmental testing & Rart 1/2 General and guidance-

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IEC 60068-2-1, Environmental testing - Part 2-1: Tests - Tests A: Cold

IEC 60068-2-2, Environmental testing - Part 2-2: Tests - Tests B: Dry heat

IEC 60068-2-6, Environmental testing - Part 2-6: Tests - Test Fc: Vibration (sinusoidal)

IEC 60068-2-11, Basic environmental testing procedures – Part 2-11: Tests – Test Ka: Salt mist

IEC 60068-2-14, Environmental testing – Part 2-14: Tests – Test N: Change of temperature

IEC 60068-2-17, Basic environmental testing procedures – Part 2-17: Tests – Test Q: Sealing

IEC 60068-2-20, Environmental testing – Part 2-20: Tests – Test T: Test methods for solderability and resistance to soldering heat of devices with leads

IEC 60068-2-21, Environmental testing – Part 2-21: Tests – Test U: Robustness of terminations and integral mounting devices

IEC 60068-2-27, Environmental testing – Part 2-27: Tests – Test Ea and guidance: Shock

IEC 60068-2-31, Environmental testing – Part 2-31: Tests – Test Ec: Rough handling shocks, primarily for equipment-type specimens

IEC 60068-2-38, Environmental testing – Part 2-38: Tests – Test Z/AD: Composite temperature/humidity cyclic test